

# **Data Sheet**



Shenzhen Deyan Electronics Co., Ltd

## 1. Scope:

This specification applies the Shielded construction chip inductor DNR4020S100MT

#### 2. Outline:

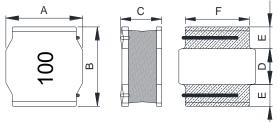
The products are used as choke coils for DC/DC converter and consist of drum core, coil, magnetic glue and terminals.

## 3. Safety Specification:

The products shall be used as secondary circuit parts, thus are not applied by any specific safety standards.

### 4. Specification:

#### 4.1. Dimensions



| Α | 4.0±0.2  | D | 2.0 Ref. |
|---|----------|---|----------|
| В | 4.0±0.2  | Е | 1.0 Ref. |
| С | 2.0 Max. | F | 3.6 Ref. |

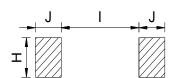
4.2. Main parts list

| No. | Part name     | Material   | Qty   |
|-----|---------------|--|-------|
| 1   | Drum Core     | Ni-Zn Ferrite or Equivalent                            | 1set  |
| 2   | Coil          | Cu/P180/Grand 1/Polyurethane enameled or<br>Equivalent | 1set  |
| 3   | Solder        | 107H or Equivalent                                     | 0.15g |
| 4   | Magnetic Glue | Ferrite Powder & Resin                                 | 0.15g |

#### 4.3. Pin Connection:



## 4.4. Recommended Land Pattern:



| ı | 1.9 Ref. |
|---|----------|
| J | 1.0 Ref. |
| Н | 3.5 Ref. |

4.5. Electrical Specifications:

|   | Part Number  | Rated<br>Inductance<br>(1)<br>(µH) | Test<br>Condition | DC<br>Resistance<br>(mΩ) | Self<br>-Resonant<br>Frequency<br>(MHz)<br>Min. | Isat (2)<br>Amperes<br>(A) | Irms(3)<br>Amperes<br>(A) | Part<br>Marking<br>Designator |
|---|--------------|------------------------------------|-------------------|--------------------------|---|----------------------------|---------------------------|-------------------------------|
| D | NR4020S100MT | 10uh±20%                           | 100kHz,1Vrms      | 215Max165Typ.            | 26  | 1.60Max.1.70Typ.           | 0.90Max.1.20Typ.          | 100                           |

<sup>(1)</sup> Open Circuit Inductance Test Parameters: 100kHz, 1.0Vrms, 0.0Adc.

exceed 125°C. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

Note: The rated current is subject to change depending on the cooli



Page: 2/o10

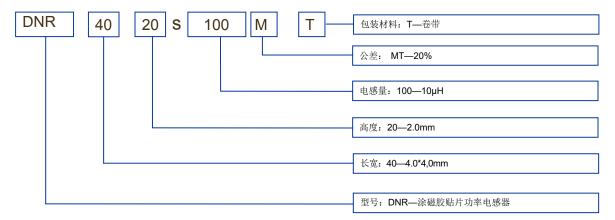
<sup>(2)</sup> Isat Amperes Typical for approximately 30% roll off (@25°C)

<sup>(3)</sup> Irms: current for an approximate ΔT of 40°C without core loss

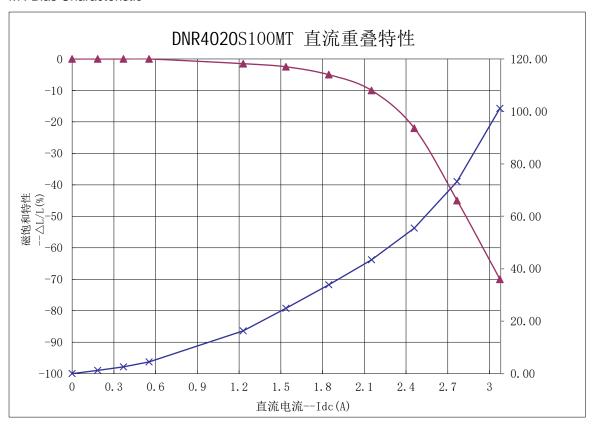
s(Ta=25°C). It is recommended that the temperature of the part not

<sup>(4)</sup> Rated current: Isat and Irms whichever is lower.

## 4.6. Ordering Code & Explanation of Part Numbers:

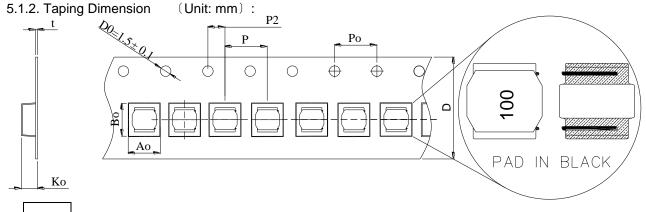


#### 4.7. Bias Characteristic





# 5. Package Specification: T=30.5 5.1. Taping Specification:5.1.1.Reel Dimension **COVER TAPE** (Unit: mm): A=330.0LABEL (Ó) G=24.5 \*CARRIER TAPE WIDTH: D G

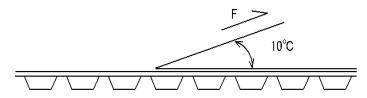


| STA        |               |     |     |              |              |              |             |              |              |             |               |             |             |             |
|------------|---------------|-----|-----|--------------|--------------|--------------|-------------|--------------|--------------|-------------|---------------|-------------|-------------|-------------|
| STA<br>YLE | Q'TY<br>(PCS) | Α   | В   | С            | D            | G            | Т           | A0           | В0           | K0          | t             | Р           | Ро          | P2          |
| 13"        | 3000          | 330 | 100 | 12.0<br>±0.2 | 12.0<br>±0.2 | 12.0<br>±0.2 | 16.4<br>Max | 4.30<br>±0.1 | 4.30<br>±0.1 | 3.2<br>±0.1 | 0.30<br>±0.05 | 8.0<br>±0.2 | 4.0<br>±0.2 | 2.0<br>±0.1 |

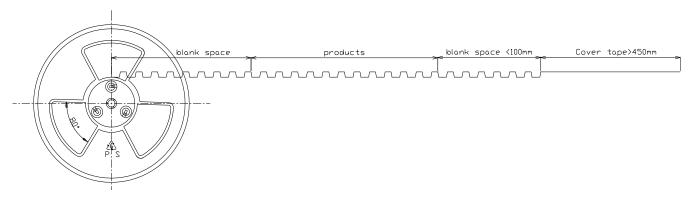
5.1.3. Tensile Strength: 5.1.3.1. Plastic tape :  $\geqq 10N$  ( $\geqq 1.0kg$  5.1.3.2.Material : PS 5.1.3.3.Cover tape :  $\geqq 5N$  ( $\geqq 0.5kgf$ )  $\geq$  10N ( $\geq$  1.0kgf)

5.1.4. Tensile Strength of Cover Tape (Ref.): F=0.2 $\sim$ 0.9N

Angel of pull 0  $\sim$  15  $^{\circ}$  opposite the forward direction, Velocity of pull: 300 mm/min.

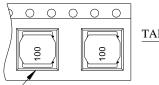


5.1.5. Packing Style of Taping (Unit: mm)





## 5.1.6. Packaging Style of Products:



TAPE DIRECTION OF FEED

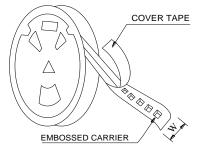
ELECTRODE SIDE

5.1.7. Packaging style of case

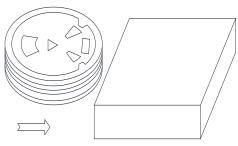
5.1.7.1. Packing cases are composed of the inner case and outer case.

5.1.7.2. Nine inners cases are put in an outer, thus 27,000 products put in an outer case.

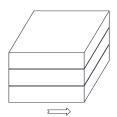
5.1.7.3. Paper cushion are placed on the upper and bottom side in the outer case

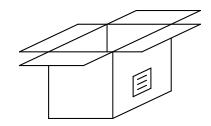


3,000 pcs in 1 reel (inner) case



3 reels in 1 reels (inner) cases





3 reels (inner) cases in 1 packaging (outer) case

5.1.8. Indication:

5.1.8.1. Label attached on reel:

Production Label



Qty.:3,000pcs



Lot No.:20210506N03

5.1.8.1. Label attached on packaging (outer) case:



Qty.:27,000pcs



Made in China

Made in China

**Production Label** 

5.1.9. Notes:

5.1.9.1. This specification defines the standard packaging style and is subject to change depending on quantity or fractions.

5.1.9.2. Inside of cases shall be filled with cushions to keep the products stable.

5.1.9.3. Inspection Certificate: Attach size data and the electric characteristic result for each shipping lot as "Inspection Certificate".



## 6. Reliability data:

| Item                    | Specified Value                        | Test Method and Remarks   |
|-------------------------|--|---|
| 1.Operating             | -40℃~+125℃                             | Including self-generated heat.                                  |
| Temperature Range       |  |   |
| 2. Storage Temperature  | -40℃~+125℃                             | $0{\sim}40{}^{\circ}{\rm C}$ for the product with taping.       |
| Range                   |  |   |
| 3.External Appearance   | The coil has no external defects.      | On visual inspection.   |
| 4.Rated current         | Within the specified tolerance         | The maximum DC value having inductance decrease within          |
|                         |  | specified value and temperature increase within 40°C by the     |
|                         |  | application of DC bias.   |
|                         |  | Inductance decrease.(Type: 30%)                                 |
| 5.Inductance            | Within the specified tolerance         | LCR Meter: HP 4194A or equivalent, 100KHz, 0.25V                |
| 6.DC Resistance         | Within the specified tolerance         | DC ohmmeter: TOS8001 or equivalent.                             |
| 7.Self resonance        | Within the specification               | Impedance analyzer/material analyzer: HP4291A ,                 |
| frequency               | ·                                      | HP4194A, 4192A or equivalent.                                   |
| 8.Temperature           | Inductance change:                     | Measurement of inductance shall be taken at temperature         |
| characteristic          | Within±15% 0~2000ppm/℃                 | range within -40 $\sim$ +125 $^{\circ}$ C.                      |
|                         | ''                                     | With reference to inductance value at +25°C, change rate        |
|                         |  | shall be calculated.  |
|                         |  | Change of maximum inductance deviation in step 1 to 5           |
|                         |  | Temperature at step 1: 25°C                                     |
|                         |  |   |
|                         |  | Temperature at step 2: Minimum operating temperature            |
|                         |  | Temperature at step 3: 25°C (Standard temperature)              |
|                         |  | Temperature at step 4: Maximum operating temperature            |
|                         |  | Temperature at step 5: 25°C and the value calculate based       |
|                         |  | on the value applicable in a normal temperature and normal      |
|                         |  | humidity shall be $\triangle L/L_{25\%} \leqslant \pm 15\%$     |
|                         |  | Measurement Equipments: HP 4194A(at 100 KHz) or                 |
|                         |  | equivalent.   |
|                         |  |   |
|                         |  |   |
| 9.Resistance to flexure | Inductance change: Within±5.0%         | The test samples shall be soldered to the test board by the     |
| of substrate            | There shall be no mechanical damage or | reflow.   |
|                         | electrical damage                      | As illustrated below, apply force in the direction of the arrow |
|                         |  | indicating until deflection of the test board reaches to 3 mm.  |
|                         |  | Test board size: 100*40*1.0 Test board material: glass          |
|                         |  | epoxy-resin   |
|                         |  | Solder cream thickness: 0.12mm.                                 |
|                         |  | Keep time: 3~5seconds Speed:0.5mm/sec                           |
|                         |  | Force Rod 10 20   |
|                         |  | R230  |
|                         |  | Board Test Sample 45±2mm 45±2mm                                 |
|                         |  | Printed board thickness: 1.0mm                                  |
|                         |  | Unit: mm  |
|                         |  |   |



| Item                     | Specified Value                                      | Test Me   | thod and R    | temarks                        |  |  |
|--------------------------|--|---|---------------|--------------------------------|--|--|
| 10.Insulation resistance | NL   | Between Coils   |               |                                |  |  |
| 11.Insulation resistance | Over 100M Ω at 100V D.C. for 1 minute.               | Between coil and core. DC 100V voltage shall be applied for   |               |                                |  |  |
|                          |  | 1 minuteacross the top  | surface and   | d the terminal of this         |  |  |
|                          |  | sample(current: 1 m A)  |               |                                |  |  |
| 12.Withstanding voltage  | No dielectric breakdown at 100V D.C. for 1           | Between coil and core. D  | C 100V vol    | tage shall be applied fo       |  |  |
|                          | minute   | 1 minuteacross the top  | surface and   | d the terminal of this         |  |  |
|                          |  | sample(current: 1 m A)  |               |                                |  |  |
| 13.Adhesion of terminal  | Shall not come off PC board.                         | The test samples shall be   | soldered t    | o the test board by the        |  |  |
| electrode                |  | reflow.   |               |                                |  |  |
|                          |  | Applied force: 10N to X a   | nd Y directi  | ions. Duration: 5s.            |  |  |
|                          |  | Solder cream thickness: (   | 0.12mm.       |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  | 10  | N 50          |                                |  |  |
|                          |  |   | N, 5s         |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   | <del>_</del>  |                                |  |  |
|                          |  | / /x  |               |                                |  |  |
|                          |  | Y   |               |                                |  |  |
| 14.Resistance to         | Inductance change: Within±10%                        | The test samples shall be   | soldered t    | o the test board by the        |  |  |
| vibration                | There shall be no mechanical damage.                 | reflow.  Then it shall be submitted to below test conditions.   |               |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  | The test samples shall be   | e soldered t  | o the test board by the        |  |  |
|                          |  | reflow.   |               |                                |  |  |
|                          |  | Then it shall be submitted  | d to below t  | est conditions.                |  |  |
|                          |  | Frequency Range   | 10~5          | 55Hz                           |  |  |
|                          |  | Total Amplitude   | 1.5mr         | m(May not exceed               |  |  |
|                          |  |   | accel         | eration 196 m/s <sup>2</sup> ) |  |  |
|                          |  | Sweeping Method   | 10Hz          | to 55Hz to 10 Hz for           |  |  |
|                          |  |   | 1 min         |                                |  |  |
|                          |  | Time  | X             | For 2 hours on                 |  |  |
|                          |  |   | Υ             | each X, Y, and Z               |  |  |
|                          |  |   | Z             | axis.                          |  |  |
|                          |  |   |               |                                |  |  |
|                          |  | Recovery: At least 2hrs of recovery under the standard condition sfter the test, followed by the measurement within the test. |               |                                |  |  |
|                          |  |   |               |                                |  |  |
| AE Oaldarah Wa           | At least 200% of conferent transitional alest and in | 48 hrs.   | aller and the | there are distance to all the  |  |  |
| 15.Solderability         | At least 90% of surface of terminal electrode is     | The test samples shall be dipped in flux, and then shall be   |               |                                |  |  |
|                          | covered by new solder.                               | preheated for 2 minutes in a temperature of 135~150°C   |               |                                |  |  |
|                          |  | and after it has been imm   |               | •                              |  |  |
|                          |  | for 5.0±1.0 seconds mol   |               |                                |  |  |
|                          |  | Flux: Methanol solution of  | •             | osin 25%.                      |  |  |
|                          |  | Solder Temperature: 245   | ±5℃           |                                |  |  |
|                          |  | Immersion depth: 0.5mn  | n.            |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   |               |                                |  |  |
|                          |  |   |               |                                |  |  |



| Item                  | Specified Value                           | Test Meth                       | nod and Remarks                                       |
|-----------------------|---|---------------------------------|---|
| 16.Resistance to      | Inductance change: Within±10%             | The test sample shall be ex     | xposed to reflow oven at 230 $\pm$                    |
| soldering heat        | No significant abnormality in appearance. | 5°C for 40 seconds, with p      | eak temperature at 260 $\pm 5^\circ\!\!\! \mathrm{C}$ |
|                       |   | 5 seconds, 2 times.             |   |
|                       |   | Test board thickness: 1.0 n     | nm  |
|                       |   | Test board material: glass      | epoxy-resin.  |
|                       |   | Reflow condition (              | temperature chart.)                                   |
|                       |   | 300                             |   |
|                       |   | 250                             | 245°C.Peak  |
|                       |   | 150 170+10°C                    | 230°C.40s   |
|                       |   | 100                             | MI~17/IS  |
|                       |   | 50                              |   |
|                       |   | 4, 4, 4, 4, 4, 4, 6             | 4 4 4 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1               |
|                       |   |                                 |   |
| 17.Thermal shock      | Inductance change: Within±10%             | The test samples shall be s     | soldered to the test board by the                     |
| 17. Thermal shock     |   | reflow. The test samples sh     | •   |
|                       | No significant abnormality in appearance. |                                 | me by step 1 to step 4 as show                        |
|                       |   | in below table in sequence      |   |
|                       |   | The temperature cycle sha       |   |
|                       |   | Conditions                      |   |
|                       |   | Step Temperature(°              | -   |
|                       |   | ` `                             | ,   |
|                       |   | 1 -40±3                         | 30±3  |
|                       |   | 2 Room temperat                 | ure Within 3  |
|                       |   | 3 +85±2                         | 30±3  |
|                       |   | 4 Room temperat                 | ure Within 3  |
|                       |   |                                 |   |
| 18.Damp heat          | Inductance change: Within±10%             | Recovery: At least 2hrs of      | recovery under the standard                           |
| 10.Bamp float         |   | ·                               | owed by the measurement with                          |
|                       | No significant abnormality in appearance. | 48 hrs.                         |   |
|                       |   |                                 | soldered to the test board by the                     |
|                       |   | reflow.                         | 50.u0.0u to the tool 20u.u 2) the                     |
|                       |   |                                 | placed in thermostatic oven set                       |
|                       |   |                                 | humidity as shown in below tab                        |
|                       |   | Temperature                     | 60±2℃   |
|                       |   | Humidity                        |   |
|                       |   |                                 | 90~95%RH  |
|                       |   | Time                            | 500±24hour  |
|                       |   |                                 |   |
| 19.Loading under damp | Inductance change: Within±10%             | Recovery: At least 2hrs of      | recovery under the standard                           |
| neat                  | No significant abnormality in appearance. | condition after the test, follo | owed by the measurement with                          |
|                       |   | 48 hrs.                         |   |
|                       |   | The test samples shall be s     | soldered to the test board by the                     |
|                       |   | reflow.                         |   |
|                       |   | The test samples shall be p     | placed in thermostatic oven set                       |
|                       |   | specified temperature and       | humidity and applied the rated                        |
|                       |   | current continuously as sho     |   |
|                       |   | Temperature                     | 60±2℃   |
|                       |   | Humidity                        | 90∼95%RH  |
|                       |   | Time                            | 500±24hour  |
|                       |   | Limo                            |   |



| Item                     | Specified Value  | Test Me  | ethod and Remarks         |               |  |  |
|--------------------------|--|--|---------------------------|---------------|--|--|
| 20.Low temperature life  | Inductance change: Within±10%  | Recovery: At least 2h  | rs of recovery under the  | standard      |  |  |
| test                     | No significant abnormality in appearance.  | condition after the test, followed by the measurement within 48 hrs. |                           |               |  |  |
|                          |  | The test samples shall b reflow.                                     | e soldered to the test bo | ard by the    |  |  |
|                          |  | After that, the test sample  | es shall be placed at tes | st conditions |  |  |
|                          |  | as shown in below table.   | ·                         |               |  |  |
|                          |  | Temperature  | -40±3℃                    |               |  |  |
|                          |  | Time   | 500 ± 24hour              |               |  |  |
| 21.High temperature life | Inductance change: Within±10%  | Recovery: At least 2h  | urs of recovery under the | standard      |  |  |
| test                     | No significant abnormality in appearance.  | condition after the test, for 48 hrs.                                | -                         |               |  |  |
|                          |  | Temperature  | <b>125</b> ±3℃            | 1             |  |  |
|                          |  | Time   | 500±24hour                | 1             |  |  |
|                          |  |  |                           |               |  |  |
| 22.Loading at high       | Inductance change: Within±10%  | The test samples shall b   | e soldered to the test bo | ard by the    |  |  |
| temperature life test    | No significant abnormality in appearance.  | reflow soldering.  Temperature                                       | 95 ⊥ 2 ℃                  | 7             |  |  |
|                          |  |  | 85±3℃                     |               |  |  |
|                          |  | Applied current Time   | Rated current             |               |  |  |
|                          |  | Time   | 500±24hour                |               |  |  |
| 23.Standard condition    | Standard test condition : Unless otherwise specified, temperature is 25 $\pm$ 15 $^{\circ}$ C and 65 $\pm$ |  |                           |               |  |  |
|                          | 20% of relative humidity.  |  |                           |               |  |  |
|                          | When there are question concerning   |  |                           |               |  |  |
|                          | measurement result : In order to provide   |  |                           |               |  |  |
|                          | correlation date, the test shall be condition of 25  |  |                           |               |  |  |
|                          | $\pm 2^{\circ}\!$                    |  |                           |               |  |  |
|                          | Inductance is in accordance with our measured  |  |                           |               |  |  |
|                          | value.   |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  |  |                           |               |  |  |
|                          |  | <u>I</u>   |                           |               |  |  |



| Item                 | Specified Value                                  | Test Method and Remarks  |
|----------------------|--|--|
| 24.Heat endurance of | Electric no variation Appearance no deformation. | Reflow hart endurance test (temperature chart.)  |
| reflow soldering     | Inductance change: Within±10%                    | 200  |
|                      | No significant abnormality in appearance.        | The test should be made under the conditions according to the chart, after the test it is kept for 2 hours under the normal temperature and humidity. Then, no mechanical and electrical defect should be found out.  The reflow test can be done twice, but the interval should be more than one hour under the normal conditions.  The reflow test conditions are based on the testing instruments available in VCOIL. |

## 7. Others:

- 7.1. The contents of this document only assures the characteristics and quality of the sole components. Regarding its use, please evaluate and check that they work correctly when fixed to your equipments.
- 7.2. We will not take any responsibility for any troubles caused by usage beyond the range that this document specifies.
- 7.3. The products in this specification are targeted for use in general electrical equipments. Please do not apply on equipments that need. Especially high reliability and/or the defects caused by the product will have direct influence on a person's life or property.
- 7.4. Period of quality assurance shall be 1 year from the date of shipment. The products must be controlled normal conditions, thus in cases where the products are put under abnormally high temperature and humidity or contamination and damage by natural disasters or other reasons, the above quality assurance period will not be valid.
- 7.5. Please return this document with signature of receipt within 30 days after our issued date. In case this document is not returned with signature of receipt within 30 days, it is seen as you have approved this document.
- 7.6. When additions or modifications are needed to this document, both parties shall discuss the revision of the document.
- 7.7. Both parties are under confidentiality obligation regarding the information contained in this document.

